



SMC-220-ARP9
W15.90xD14.90xH1.50

PIN 数(Number of contacts) : 9PIN

耐电压(Withstand voltage) : 500V AC for 1 min

操作方式(Operation mode): 翻盖式/HINGE

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PER PIN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 卷带/Tape & Reel (TR)

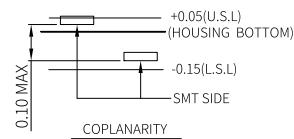
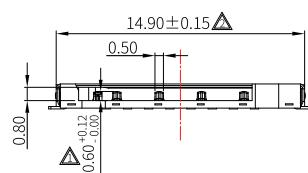
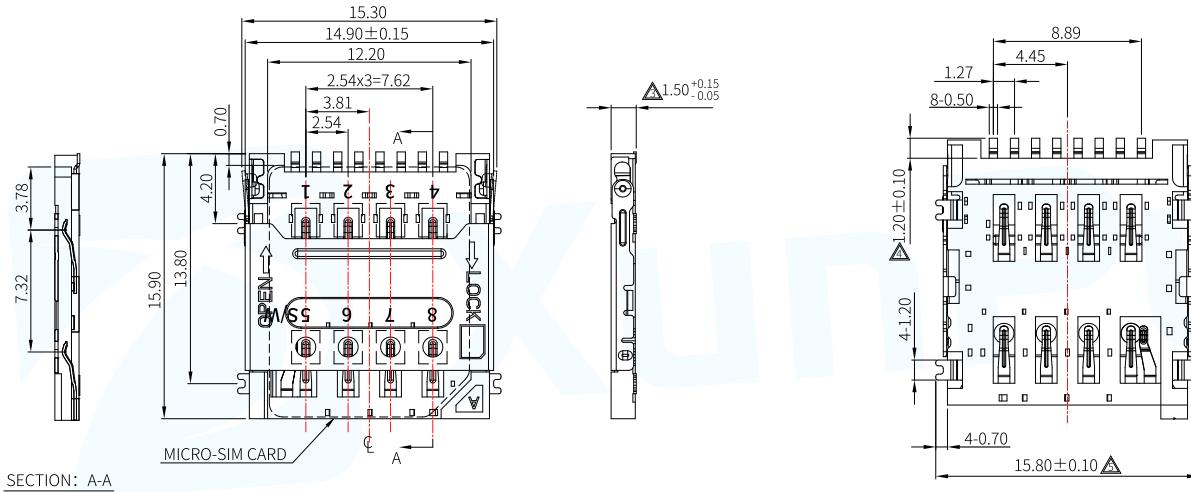
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 1,300/PCS

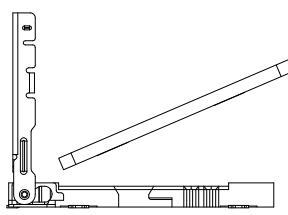
外形尺寸(UNIT:MM) / Size Chart

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更多资料请参考技术选型档!



ITEM	PART NAME	Q'TY	MATERIAL	DESCRIPTION
1	Shell	1	SUS304-H,T=0.12	AU/Ni PLATING
2	Base Insulator	1	LCP+GF30%	BLACK
3	Terminal	8	C5210-EH,T=0.12	Au 5u" PLATING



STEP 1 INSERT Micro-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NOTES

1.MATERIAL:

1-1.HOUSING: THERMOPLASTIC,UL 94-V0

1-2.TERMINAL: PHOSPHOR BRONZE,T=0.15

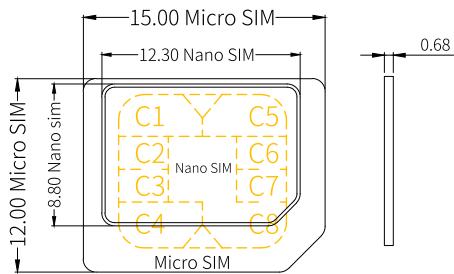
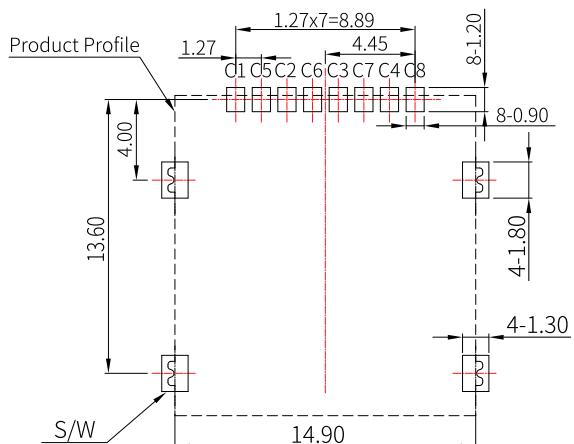
1-3.SHELL: STAINLESS STEEL,T=0.15

2.FINISHED:

2-1.TERMINAL: Ni PLATED UNDER,Au PLATED ON CONTACT AREA,G/F PLATED ON SOLDERTAIL

2-2.SHELL: Ni PLATED UNDER,G/F PLATED ON SOLDERTAIL

MICRO SIM



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

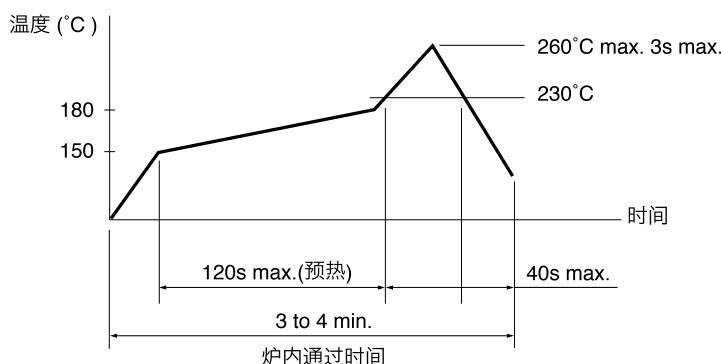
WIHDRAWAL CARD	INSERT CARD
GROUND PIN <input checked="" type="checkbox"/> Switch Pin <input checked="" type="checkbox"/> (C5) <input checked="" type="checkbox"/>	GROUND PIN <input checked="" type="checkbox"/> Switch Pin <input checked="" type="checkbox"/> (C5) <input checked="" type="checkbox"/>

NORMALLY OPEN IN THE CONNECTOR
WHEN THE CARD INSERT, THE SWITCH IS CLOSE

焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



注:

- 加热方式:以远红外线上下加热方式。
- 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
- 固定方式:采用耐热胶带。

手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.